

REMARKS

Claims 1-14 are now pending in the application. Minor amendments have been made to the claims to simply overcome the objections and rejections of the claims. The amendments do not alter the scope of the claims as originally filed and, thus, are not narrowing amendments. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

DRAWINGS

The office action states that Figure 8 should be designated by a legend such as --Prior Art--. Applicant submits a request for approval of drawing changes concurrently herewith adding the legend --Prior Art-- to Figure 8. Accordingly, this objection should be moot.

SPECIFICATION

The specification stands objected to as failing to provide proper antecedent basis for the claimed subject matter. This objection is respectfully traversed. Notwithstanding, claim 8 is amended to change "external terminals" to --wirings--. Support for this claimed subject matter can be found at least at page 11, lines 15-24 and page 16, lines 5-14. Accordingly, this objection should be moot.

REJECTIONS UNDER 35 U.S.C. § 112

Claims 3 and 6-12 stand rejected under 35 U.S.C. § 112, second paragraph. This rejection is respectfully traversed. Applicant respectfully disagrees

with the interpretation of the term "terminals" as enumerated in the office action. More particularly, in describing the embodiment of Figs. 1 and 2, the specification at page 11, line 13 states that "lands 14 are formed as substrate-side terminals". At page 13, line 13, the specification states that "bumps 16 [are formed] as opposing-side terminals". While the specification distinguishes between the "bumps" of the IC chip and the "terminals" of the compression-bond-connection substrate, the term "terminals" should be interpreted when read in light of the specification as either terminals, bumps, lands, or any combination thereof.

The office action states that claim 6 is confusing because it is allegedly unclear whether the target object of claim 1 is one of the pair of substrates of claim 6 or different. Claim 6 is amended to recite that the compression-bonding target object is a liquid crystal device including a pair of substrates opposing each other and a liquid crystal sealed between the substrates.

The office action states that claim 8 is inconsistent with the specification and the drawings because it allegedly is unclear to which terminals of which drawings the recited "external terminals" refer. Although applicant does not necessarily agree, claim 8 is amended to change "external terminals" to --wirings--.

The office action states that claim 8 is also indefinite for the same reasons applied to claim 3. This rejection is confusing inasmuch as neither an IC chip nor bumps are recited in claim 8. Clarification is respectfully requested.

ALLOWABLE SUBJECT MATTER

Claims 3, 7, and 9-12 were deemed allowable if rewritten to overcome the rejections under 35 U.S.C. § 112, second paragraph. As set forth in greater detail above, all of the outstanding rejections are addressed herein. As such, claims 3, 7, and 9-12 should be in condition for allowance.

Claims 6 and 8 were deemed allowable if rewritten or amended to overcome the rejections under 35 U.S.C. § 112, second paragraph. As set forth in greater detail above, all of the outstanding rejections are addressed herein. As such, claims 6 and 8 should be in condition for allowance.

Applicant acknowledges with thanks the indication that claims 1, 2, 4 and 5 are allowed.

NEW CLAIMS

New claims 13 and 14 are presented herein. These claims are similar to originally filed claim 8. Claim 13 retains the original "target-object" language while claim 14 calls for bumps and lands. Favorable consideration of these new claims is respectfully requested.

COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

The record should reflect that applicant does not necessarily agree with each statement in the reasons for allowance. For example, while applicant believes the claims are allowable, applicant may not unequivocally agree that patentability resides solely in the specific feature or combination of features identified, or that each feature or combination of features identified is required for patentability, or that equivalence of any

of the recited features are outside the scope of the claims. Moreover, to the extent the reasons for allowance do not separately address the subject matter of all the claims, applicant does not acquiesce to any inference that the non-addressed claims fail to present other reasons for patentability apart from the patentability of the claims which were specifically addressed by the examiner.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

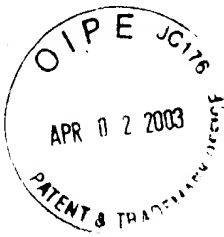
Respectfully submitted,

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ATTACHMENT FOR CLAIM AMENDMENTS

The following is a marked up version of each amended claim in which underlines indicates insertions and brackets indicate deletions.

6. (Twice Amended) A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is a [A] liquid crystal device [comprising] including a pair of substrates opposing each other[,] and a liquid crystal sealed between the substrates[, and a compression-bond-connection substrate to be connected at least to one of the pair of substrates, characterized in that the compression-bond-connection substrate is as stated in Claim 1].

8. (Amended) A liquid crystal device comprising:
a substrate having first and second sides;
a liquid crystal panel opposed to the first side of the substrate [a target object];

a plurality of external-connecting terminals formed on the liquid crystal panel [said target object];

[a substrate opposite said target object, said substrate having first and second sides;]

a plurality of substrate-side terminals formed on [said] the first side of [said] the substrate and opposed to the external-connecting [opposite said] terminals [formed on said target object];

an adhesive material disposed between [said target object and said] the

substrate and the liquid crystal panel;

a plurality of wirings formed [external terminals form] on [said] the second side of [said] the substrate [and aligned with select ones of said plurality of terminals formed on said first side of said substrate]; and

a [plurality of] compensation [members] member formed on [said] the second side of [said] the substrate [and aligned with a remainder of said plurality of terminals formed on said first side of said substrate].

9. (Amended) The liquid crystal device of Claim 8, [characterized in that said] the compensation [members have] member having substantially the same thickness as [said external terminals] the wirings.